



# OL-NX20P3000UK

wafer level chip-size package; 16 bumps

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	X (other)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-11-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.93	-	1.96	1.99	mm
E	package width	1.93	-	1.96	1.99	mm
A	seated height	0.508	-	0.54	0.572	mm
A <sub>2</sub>	package height	0.275	-	0.3	0.325	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	16	-	

## 2. Package outline

Fig. 1. Package outline WLCSP (OL-NX20P3000UK)



### 3. Legal information

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